

QUADRUPLER LOW-POWER DIFFERENTIAL RECEIVER

Check for Samples: [SN55LBC173-HIREL](#)

FEATURES

- Meets EIA Standards RS-422-A, RS-423-A, RS-485, and CCITT V.11
- Designed to Operate With Pulse Durations as Short as 20 ns
- Designed for Multipoint Bus Transmission on Long Bus Lines in Noisy Environments
- Input Sensitivity: ± 200 mV
- Low-Power Consumption: 20 mA (Max)
- Open-Circuit Fail-Safe Design

DESCRIPTION

The SN55LBC173 is a monolithic quadruple differential line receiver with 3-state outputs designed to meet the requirements of the EIA standards RS-422-A, RS-423-A, RS-485, and CCITT V.11. This device is optimized for balanced multipoint bus transmission at data rates up to and exceeding 10 million bits per second. The four receivers share two ORed enable inputs, one active when high, the other active when low. Each receiver features high input impedance, input hysteresis for increased noise immunity, and input sensitivity of ± 200 mV over a common-mode input voltage range of 12 V to -7 V. Fail-safe design ensures that if the inputs are open circuited, the output is always high. The SN55LBC173 is designed using the Texas Instruments proprietary LinBiCMOS™ technology that provides low power consumption, high switching speeds, and robustness.



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ORDERING INFORMATION⁽¹⁾

T _A	PACKAGE	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	KGD	SN55LBC173MKGD1	NA
		SN55LBC173MKGD2	NA

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

BARE DIE INFORMATION

DIE THICKNESS	BACKSIDE FINISH	BACKSIDE POTENTIAL	BOND PAD METALLIZATION COMPOSITION	BOND PAD THICKNESS
10.5 mils.	Silicon with backgrind	Floating	AlSi(1%)Cu(0.5%)TiW	1850 nm

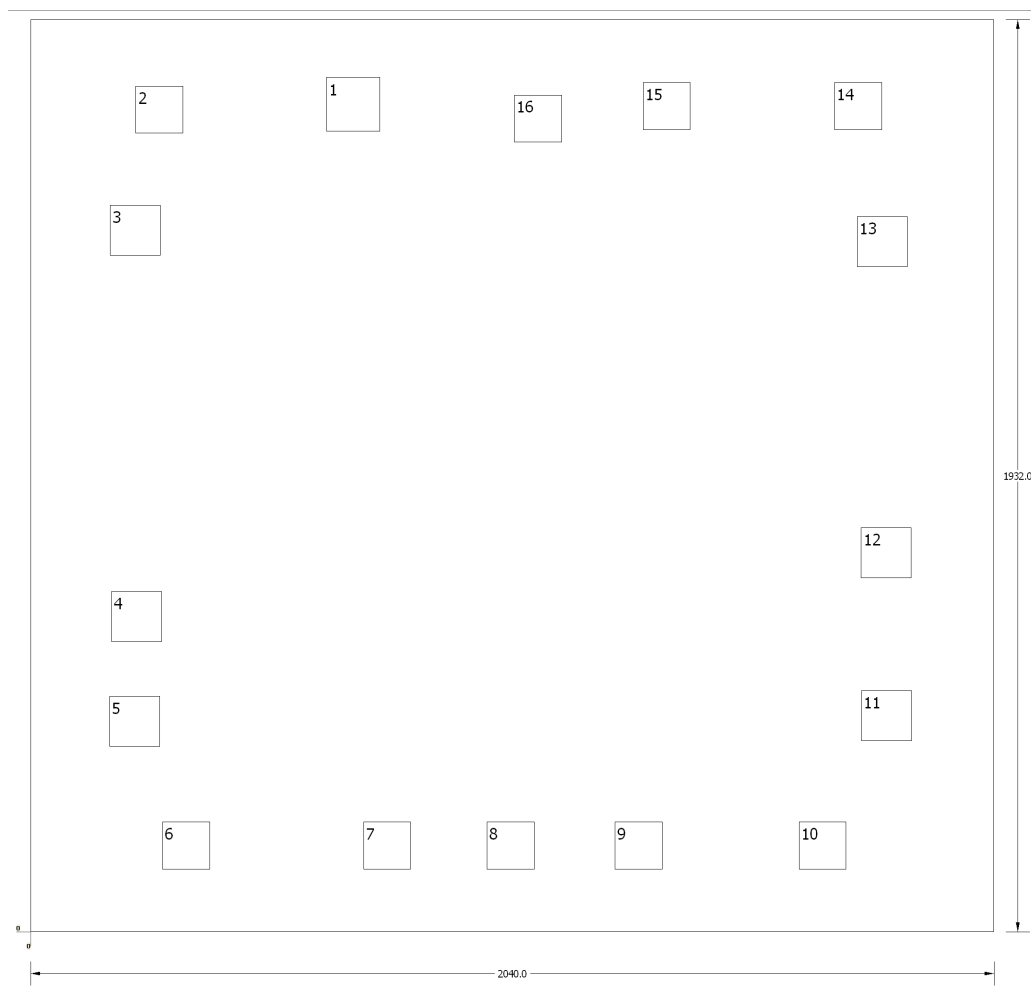


Table 1. Bond Pad Coordinates in Microns

DESCRIPTION	PAD NUMBER	X MIN	Y MIN	X MAX	Y MAX
1B	1	626.5	1695	740.5	1809.5
1A	2	222.5	1690.7	323	1791.3
1Y	3	167.9	1432.1	274.8	1539
G	4	171.4	614.1	278.3	721
2Y	5	166.6	392.1	273.5	499
2A	6	279.2	132	379.7	232.6
2B	7	704.8	132	805.3	232.6
GND	8	966.2	132	1066.7	232.6
3B	9	1237.2	132	1337.7	232.6
3A	10	1626.7	132	1727.2	232.6
3Y	11	1758.7	403.7	1865.6	510.6
$\overline{G}$	12	1758.5	749	1865.4	855.9
4Y	13	1750.1	1408.4	1857	1515.3
4A	14	1702.2	1698.4	1802.7	1799
4B	15	1296.7	1698.4	1397.2	1799
VCC	16	1024.2	1671.9	1124.7	1772.5

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range unless otherwise noted

	Value	UNIT
V _{CC} Supply voltage range ⁽²⁾	–0.3 to 7	V
V _I Input voltage range, (A or B inputs)	±25	V
V _{ID} Differential input voltage ⁽³⁾	±25	V
Data and control voltage range	–0.3 to 7	V
T _A Operating free-air temperature range	–55 to 125	°C
T _{stg} Storage temperature range	–65 to 150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.
- (3) Differential input voltage is measured at the noninverting input with respect to the corresponding inverting input.

RECOMMENDED OPERATING CONDITIONS

	MIN	TYP	MAX	UNIT
V _{CC} Supply voltage	4.75	5	5.25	V
V _{IC} Common-mode input voltage	–7		12	
V _{IH} High-level input voltage	2			
V _{IL} Low-level input voltage			0.8	
V _{ID} Differential input voltage	–6		6	
I _{OH} High-level output current			–8	mA
I _{OL} Low-level output current			16	mA
T _A Operating free-air temperature	–55		125	°C

ELECTRICAL CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	I _O = −8 mA				0.2	V
V _{IT−}	Negative-going input threshold voltage	I _O = 8 mA		−0.2			
V _{hys}	Hysteresis voltage (V _{IT+} − V _{IT−})				45		mV
V _{IK}	Enable input clamp voltage	I _I = −18 mA			−0.9	−1.5	V
V _{OH}	High-level output voltage	V _{ID} = −200 mV, I _{OH} = −8 mA		3.5	4.5		V
V _{OL}	Low-level output voltage	V _{ID} = −200 mV, I _{OL} = 8 mA			0.3	0.5	V
		V _{ID} = −200 mV, I _{OL} = 8 mA, T _A = 125°				0.7	
I _{OZ}	High-impedance-state output current	V _O = 0 V to V _{CC}				±20	μA
I _I	Bus input current	A or B inputs	V _{IH} = 12 V, V _{CC} = 5 V	Other inputs at 0 V	0.7	1.15	mA
			V _{IH} = 12 V, V _{CC} = 0 V		0.8	1.15	
			V _{IH} = −7 V, V _{CC} = 5 V		−0.5	−0.9	
			V _{IH} = −7 V, V _{CC} = 0 V		−0.4	−0.9	
I _{IH}	High-level input current	V _{IH} = 5 V				±20	μA
I _{IL}	Low-level input current	V _{IL} = 0 V				−20	μA
I _{OS}	Short-circuit output current	V _O = 0			−80	−120	mA
I _{CC}	Supply current	Outputs enabled, I _O = 0, V _{ID} = 5 V			11	20	mA
		Outputs disabled			0.9	1.4	

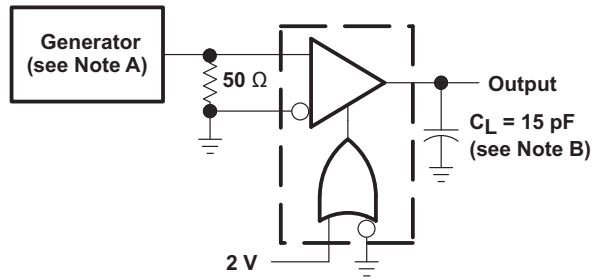
(1) All typical values are at 25°C and with a 5 V supply.

SWITCHING CHARACTERISTICS

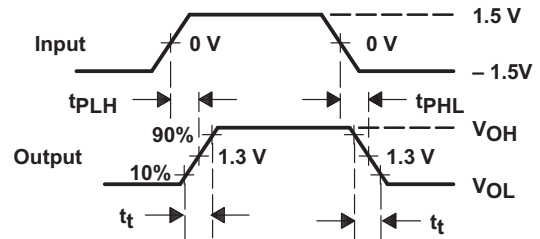
V_{CC} = 5 V, C_L = 15 pF, over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T _A	MIN	TYP	MAX	UNIT
t _{PHL}	Propagation delay time, high-to-low-level output	V _{ID} = –1.5 V to 1.5 V, See Figure 1	25°C	11	22	30	ns
			–55°C to 125°C	11		35	
t _{PLH}	Propagation delay time, low-to-high-level output	V _{ID} = –1.5 V to 1.5 V, See Figure 1	25°C	11	22	35	ns
			–55°C to 125°C	11		35	
t _{PZH}	Output enable time to high level	See Figure 2	25°C		17	40	ns
			–55°C to 125°C			45	
t _{PZL}	Output enable time to low level	See Figure 3	25°C		18	30	ns
			–55°C to 125°C			35	
t _{PHZ}	Output disable time from high level	See Figure 2	25°C		30	40	ns
			–55°C to 125°C			55	
t _{PLZ}	Output disable time from low level	See Figure 3	25°C		25	40	ns
			–55°C to 125°C			45	
t _{sk(p)}	Pulse skew ((t _{PHL} – t _{PLH}))	See Figure 1	25°C		0.5	6	ns
			–55°C to 125°C			7	
t _t	Transition time	See Figure 1	25°C		5	10	ns
			–55°C to 125°C			16	

PARAMETER MEASUREMENT INFORMATION



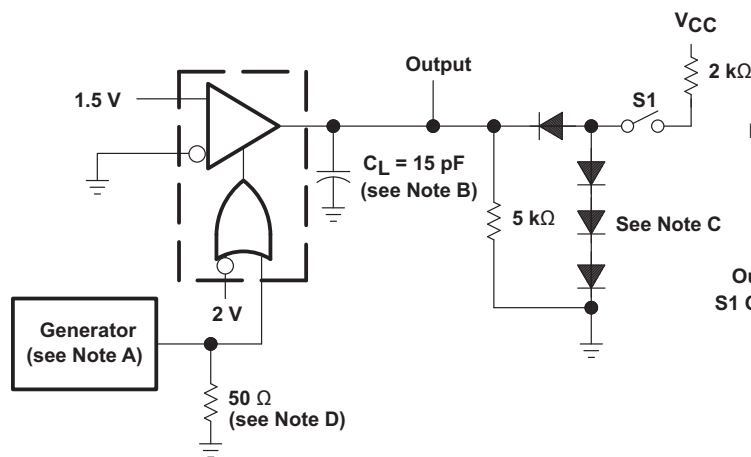
TEST CIRCUIT



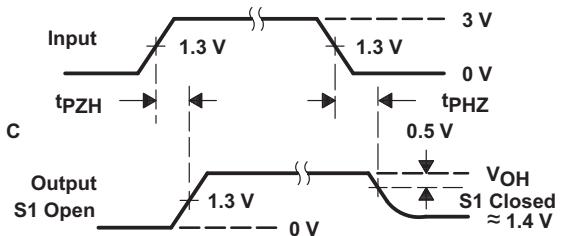
VOLTAGE WAVEFORMS

- The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle $\leq 50\%$, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50 \Omega$.
- C_L includes probe and jig capacitance.

Figure 1. t_{pd} and t_t Test Circuit and Voltage Waveforms



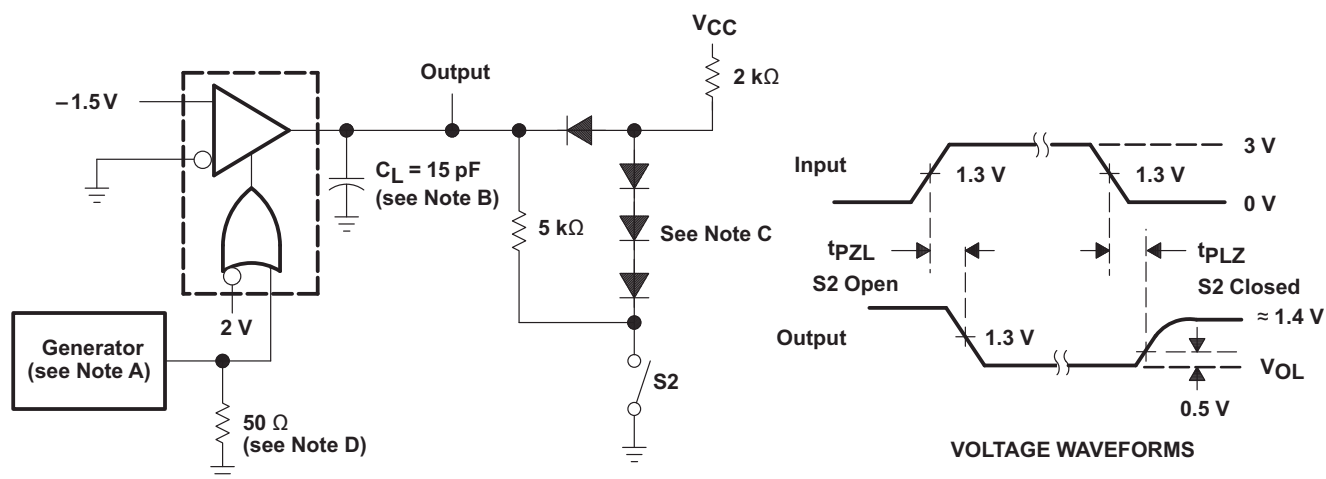
TEST CIRCUIT



VOLTAGE WAVEFORMS

- The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle $\leq 50\%$, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50 \Omega$.
- C_L includes probe and jig capacitance.
- All diodes are 1N916 or equivalent.
- To test the active-low enable $\overline{G}$, ground G and apply an inverted input waveform to $\overline{G}$.

Figure 2. t_{pHZ} and t_{pZH} Test Circuit and Voltage Waveforms

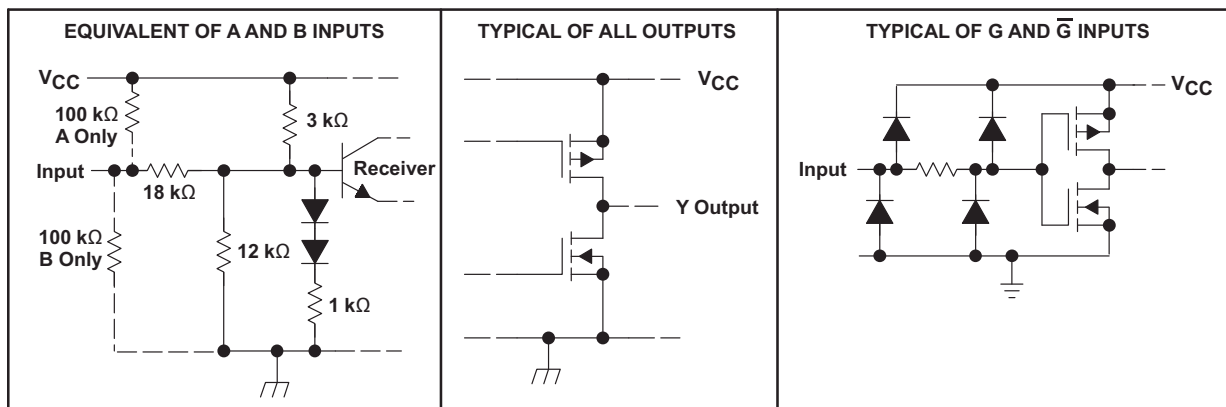
PARAMETER MEASUREMENT INFORMATION (continued)

- TEST CIRCUIT**
- The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle $\leq 50\%$, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50 \Omega$.
 - C_L includes probe and jig capacitance.
 - All diodes are 1N916 or equivalent.
 - To test the active-low enable $\overline{G}$, ground G and apply an inverted input waveform to $\overline{G}$.

Figure 3. t_{PZL} and t_{PLZ} Test Circuit and Voltage Waveforms

DEVICE INFORMATION

EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS



FUNCTION TABLE (EACH RECIEVER)

DIFFERENTIAL INPUTS	ENABLES		OUTPUT
A - B	G	$\bar{G}$	Y
$V_{ID} \geq 0.2 \text{ V}$	H	X	H
	X	L	H
$-0.2 < V_{ID} < 0.2 \text{ V}$	H	X	?
	X	L	?
$V_{ID} \leq -0.2 \text{ V}$	H	X	L
	X	L	L
X	L	H	Z
Open circuit	H	X	H
	X	L	H

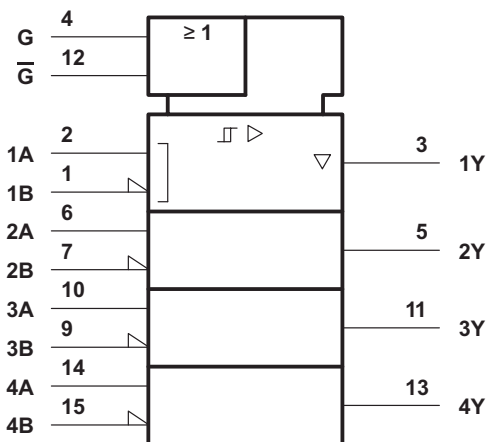


Figure 4. Logic Symbol

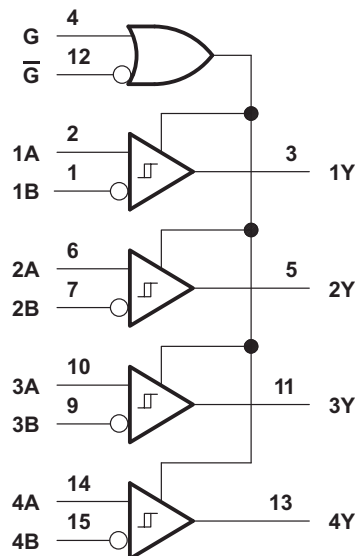


Figure 5. Logic Diagram (Positive Logic)

TYPICAL CHARACTERISTICS

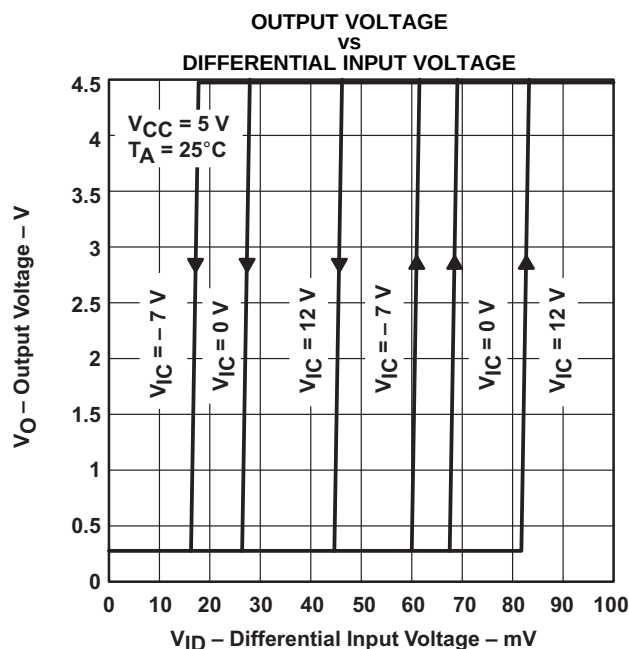


Figure 6.

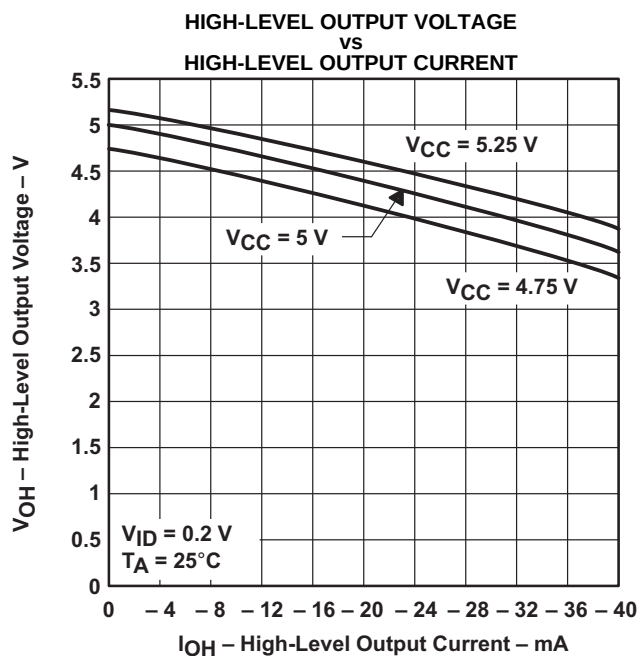


Figure 7.

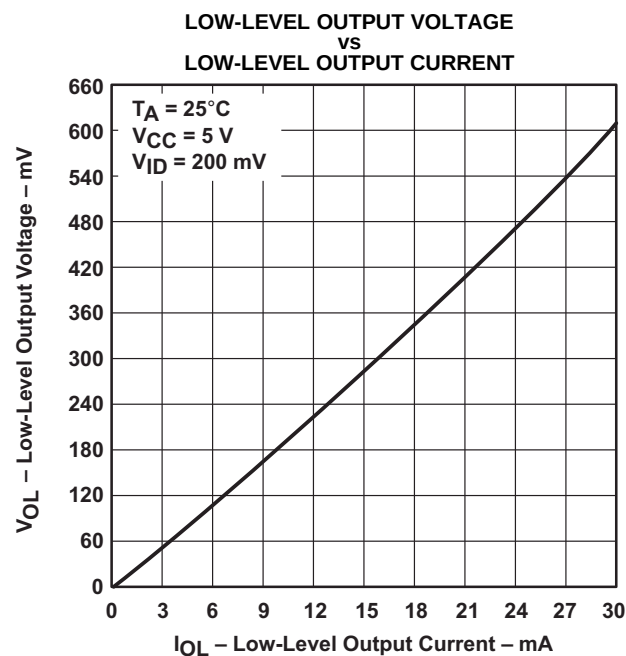


Figure 8.

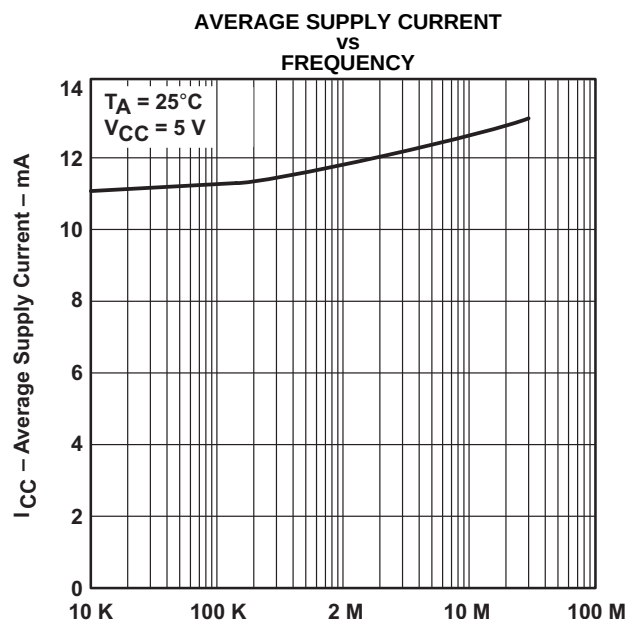
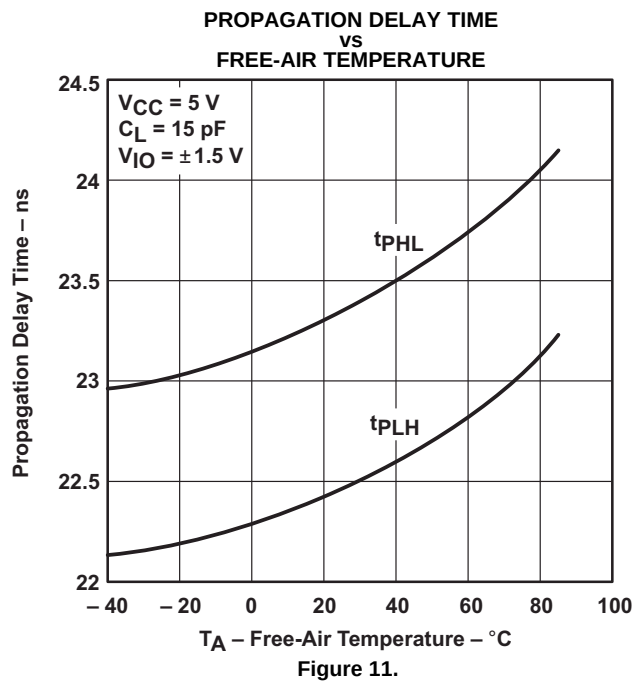
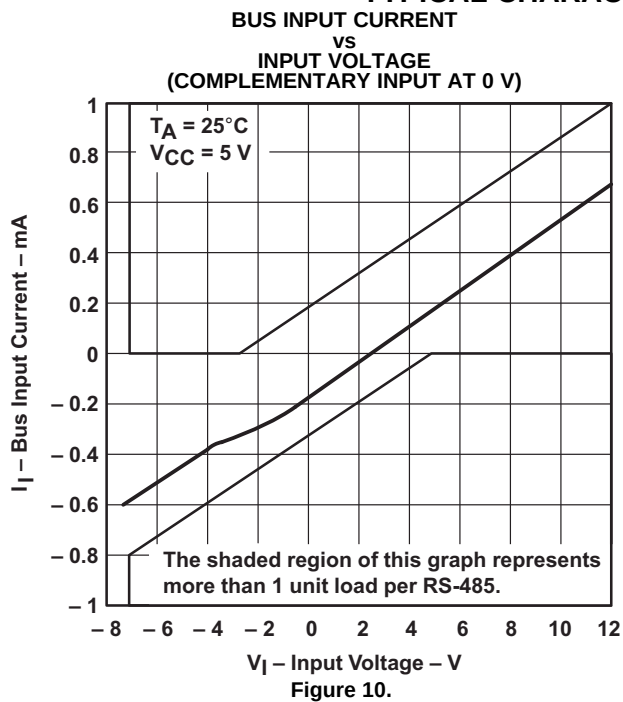


Figure 9.

TYPICAL CHARACTERISTICS (continued)



PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN55LBC173MKGD1	Active	Production	XCEPT (KGD) 0	100 TUBE	No	Call TI	N/A for Pkg Type	-55 to 125	
SN55LBC173MKGD1.A	Active	Production	XCEPT (KGD) 0	100 TUBE	No	Call TI	N/A for Pkg Type	-55 to 125	
SN55LBC173MKGD2	Active	Production	XCEPT (KGD) 0	10 TUBE	-	Call TI	Call TI	-55 to 125	
SN55LBC173MKGD2.A	Active	Production	XCEPT (KGD) 0	10 TUBE	-	Call TI	Call TI	-55 to 125	

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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